

MATERIAL DECLARATION SHEET



Material Number	PTVS3-380C-TH			
Product Line	Semiconductor Products			
Compliance Date	September 1 st 2014			
RoHS Compliant	Yes	MSL	Not Applicable	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.559500	Bisphenol Copolymer Alumina Trihydrate Fused Silica Hydrated Iron Oxide Titanium Dioxide Melamine Cyanurate Amine Adduct	1675-54-3 25085-99-8 14464-46-1 40039-93-8 51274-00-1 13463-67-7 Trade Secret	60.00 15.00 20.00 1.50 1.50 1.50 0.50	7.06 1.76 2.35 0.18 0.18 0.18 0.06	11.76
2	Electrodes	Copper	2.940894	Copper Silver Other	7440-50-8 7440-22-4 -	99.10 0.40 0.50	61.26 0.25 0.31	61.82
3	Terminations	Copper	0.469460	Copper Other	7440-50-8 -	99.50 0.50	9.82 0.05	9.87
4	Termination Finish	Silver	0.002696	Silver	7440-22-4	100.00	0.06	0.06
5	Chip	Silicon Die	0.336158	Silicon Aluminium Nickel Gold	7440-21-3 7429-90-5 7440-02-0 7440-57-5	86.30 4.79 8.49 0.41	6.10 0.34 0.60 0.03	7.07
6	Die Attach	Solder	0.176904	Lead Tin Silver	7439-92-1 7440-31-5 7440-22-4	92.50 5.00 2.50	3.44 0.19 0.09	3.72
7	Die Coating	Silicone	0.271488	Polysiloxane Chromium Sesquioxide Fumed Silica Filler	63148-62-9 1308-38-9 112945-52-5 trade secret	22.11 5.67 11.11 61.11	1.26 0.32 0.63 3.49	5.71
			Total Weight	4.757100				